

## Claims

1. Encapsulation for an organic electronics component which is essentially manufactured from a molten mass of a metallic alloy.
2. Encapsulation according to claim 1, in which the alloy is present as a molten mass in a temperature range of 30 to 200°C.
3. Encapsulation according to one of claims 1 or 2, in which the metallic alloy in a solidified form, provides a tight seal against moisture and/or oxidizing gases
4. Encapsulation according to one of the preceding claims, in which the alloy comprises at least one metal, selected from the following group of metals: Cadmium, tin, bismuth, lead, indium, mercury and/or silver.
5. Encapsulation according to one of the preceding claims, in which the thickness of the encapsulation layer amounts to between 1 and 700µm.
6. Method for encapsulating an electronics component by applying the molten mass of a metallic alloy
7. Method according to claim 6, in which the molten mass is applied by means of a printing process
8. Method according to claim 6 or 7, in which the molten mass solidifies on the organic electronics component

9. Method according to one of claims 6 to 8, in which an insulating intermediate layer is applied to the organic electronics component prior to encapsulation.